

Electronic Acknowledgement Receipt

EFS ID:	3387509
Application Number:	10580361
International Application Number:	
Confirmation Number:	1718
Title of Invention:	Production Of Semiconductor Substrates With Buried Layers By Joining (Bonding) Semiconductor Wafers
First Named Inventor/Applicant Name:	Roy Knechtel
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Filer:	Richard C. Stevens/Judith Damewood
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Attorney Docket Number:	LEO 003 PA
Receipt Date:	02-JUN-2008
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Application Type:	U.S. National Stage under 35 USC 371

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Submitted with Payment	no
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File Listing:

Document Number	Document Description	File Name	File Size(Bytes) /Message Digest	Multi Part /.zip	Pages (if appl.)
1	Power of Attorney	LEO003PA_Power_of_Attorney.pdf	135291 0710c89e70c52e3e42c31121a1ccfc38571a7d5a	no	1

Warnings:

Information:

2	Assignee showing of ownership per 37 CFR 3.73(b).	LEO003PA_Statement.pdf	248361 dafc9258a7defcace211559a77be4bf8b06b6c5a	no	2
Warnings:					
Information:					
3	Information Disclosure Statement Letter	LEO003PA_Supplemental_IDS_cover.pdf	39611 77fd09abe1c408ea86234f4d845a040bd5b1a8	no	2
Warnings:					
Information:					
4	Information Disclosure Statement (IDS) Filed	LEO003PA_Supplemental_IDS_SB08B.pdf	122709 1ea01c85839cc5d7a7be247c4447ba9cd8ef511	no	1
Warnings:					
Information:					
This is not an USPTO supplied IDS fillable form					
5	NPL Documents	LEO003PA_Semiconductor WaferBonding_Part1_NPL.pdf	20134789 1eeb5a0243599bf2a519125fcd272f4e52e7cd	no	80
Warnings:					
Information:					
6	NPL Documents	LEO003PA_Semiconductor WaferBonding_Part2_NPL.pdf	23151027 6cd419437d7f749048392bf07c75b5ca0c22f396	no	80
Warnings:					
Information:					
Total Files Size (in bytes):			43831788		
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